

30V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	RDS(ON) Max	I _D T _A = +25°C
30V	$0.12\Omega @ V_{GS} = 10V$	3.0A
307	$0.18\Omega @ V_{GS} = 4.5V$	2.5A

Description

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

Applications

- DC-DC Converters
- Power Management Functions
- Backlighting

Features and Benefits

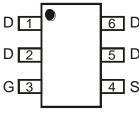
- Low Input Capacitance
- Low On-Resistance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

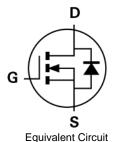
- Case: SOT26
- Case Material: Molded Plastic, "Green" Molding Compound;
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Tin Finish Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208 (€3)
- Weight: 0.018 grams (Approximate)







Top View Pin Configuration



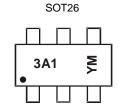
Ordering Information (Note 4)

Part Number	Case	Packaging
ZXMN3A01F6TA	SOT26	3 000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



3A1 = Product Type Marking Code YM = Date Code Marking Y or \overline{Y} = Year (ex: C = 2015) M or \overline{M} = Month (ex: 9 = September)

Date Code Key

Year	2015		2016	2017		2018	2019		2020	2021		2022
Code	С		D	Е		F	G		Н	ı		J
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Drain-Source Voltage	V_{DSS}	30	V
Gate-Source Voltage	V_{GSS}	±20	V
Continuous Drain Current, V _{GS} = 10V	I _D	3.0 2.4 2.4	А
Maximum Body Diode Forward Current (Note 6)	Is	2.4	Α
Pulsed Drain Current (Note 7)	I _{DM}	10	Α
Pulsed Source Current (Note 7)	I _{SM}	10	Α

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units	
Total Power Dissipation Linear Derating Factor	T _A = +25°C (Note 5)	P _D	1.1 8.8	W mW/°C
Total Power Dissipation Linear Derating Factor	T _A = +25°C (Note 6)	P _D	1.7 13.6	W mW/°C
Thermal Resistance, Junction to Ambient	Steady State (Note 5)	Б	113	°C/W
Thermal Resistance, Junction to Ambient	Steady State (Note 6)	$R_{\theta JA}$	70	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C	

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)							
Drain-Source Breakdown Voltage	BV _{DSS}	30	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	0.5	μA	$V_{DS} = 30V$, $V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 9)							
Gate Threshold Voltage	$V_{GS(TH)}$	1.0	_	_	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
Static Drain-Source On-Resistance (Note 8)	D	_	0.106	0.12	Ω	V _{GS} = 10V, I _D = 2.5A	
Static Drain-Source On-Resistance (Note 8)	R _{DS(ON)}		_	0.18	12	V _{GS} = 4.5V, I _D = 2.0A	
Diode Forward Voltage (Note 8)	V _{SD}		0.84	0.95	V	V _{GS} = 0V, I _S = 1.7A	
Forward Transconductance (Notes 8 & 10)	9 _{fs}		3.5	_	S	V _{DS} = 4.5V, I _D = 2.5A	
DYNAMIC CHARACTERISTICS (Note 10)							
Input Capacitance	C _{iss}	_	190	_		V _{DS} = 25V, V _{GS} = 0V f = 1.0MHz	
Output Capacitance	Coss	_	38	_	pF		
Reverse Transfer Capacitance	C _{rss}	_	20	_		1 = 1.0ivii 12	
Total Gate Charge (V _{GS} = 5.0V)	Qg	_	2.3	_		V 45V 1 0 5A	
Total Gate Charge (V _{GS} = 10V)	Qg	_	3.9	_	nC		
Gate-Source Charge	Q _{gs}	_	0.6	_	IIC	$V_{DS} = 15V, I_D = 2.5A$	
Gate-Drain Charge	Q_{gd}	_	0.9	_			
Turn-On Delay Time	t _{D(ON)}		1.7	_			
Turn-On Rise Time	t _R		2.3	_	ns	$V_{GS} = 10V, V_{DD} = 15V, R_G = 6.0\Omega,$	
Turn-Off Delay Time	t _{D(OFF)}	_	6.6	_	115	I _D = 2.5A	
Turn-Off Fall Time	t _F		2.9	_			
Body Diode Reverse Recovery Time	t _{RR}		17.7	_	ns	I _F = 2.5A, dl/dt = 100A/μs	
Body Diode Reverse Recovery Charge	Q_{RR}		13.0	_	nC	1 2.5Λ, αι/αι = 100Λ/μ5	

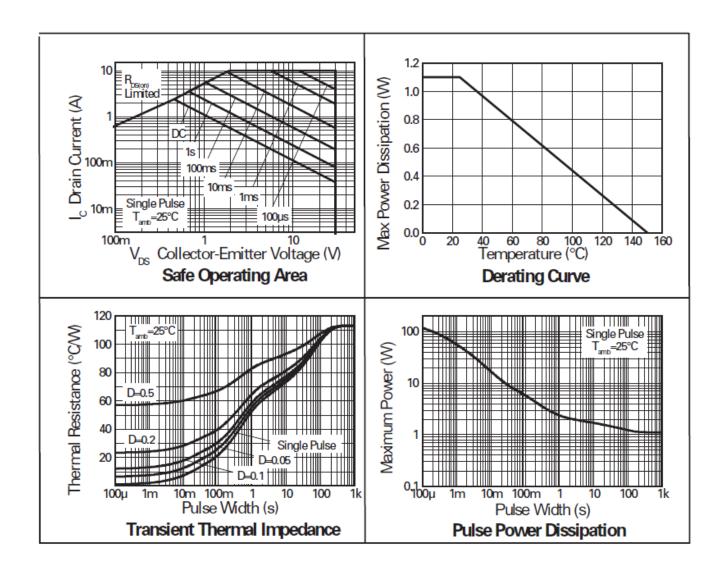
5. For a device surface mounted on 25mm x 25mm FR-4 PCB with high coverage of single sided 1oz copper, in still air conditions.

To ra device surface mounted on FR-4 PCB measured at t ≤5 secs.
 Repetitive rating 25mm x 25mm FR-4 PCB, D = 0.05, pulse width 10µs - pulse width limited by maximum junction temperature. Refer to Transient Thermal Impedance graph.
 Measured under pulsed conditions. Width=300µs. Duty cycle ≤ 2%.
 Short duration pulse test used to minimize self-heating effect.
 Currenteed by design. Not subject to product testing.

^{10.} Guaranteed by design. Not subject to product testing.

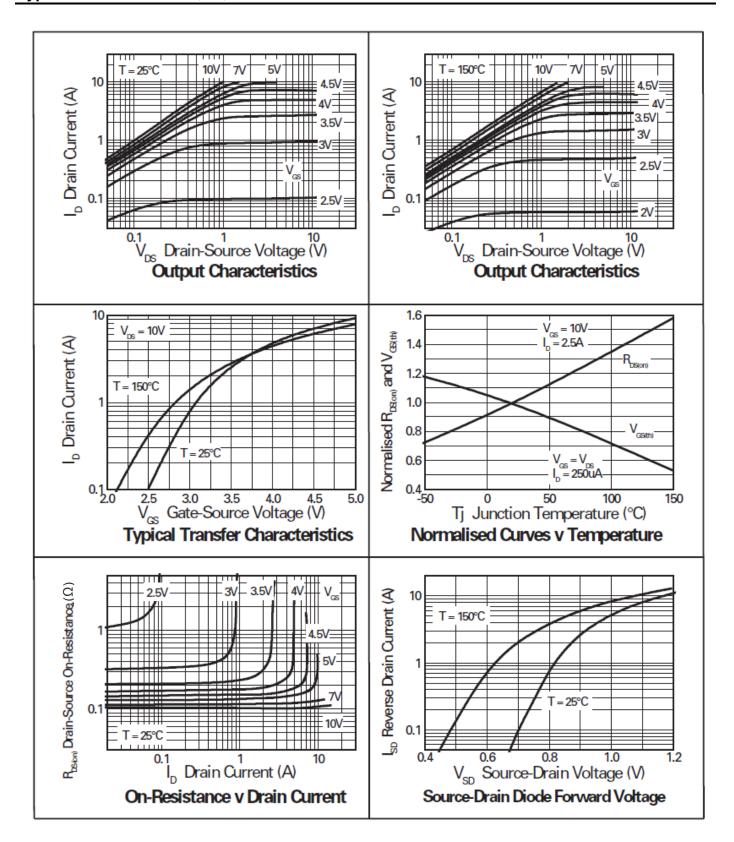


Typical Characteristics



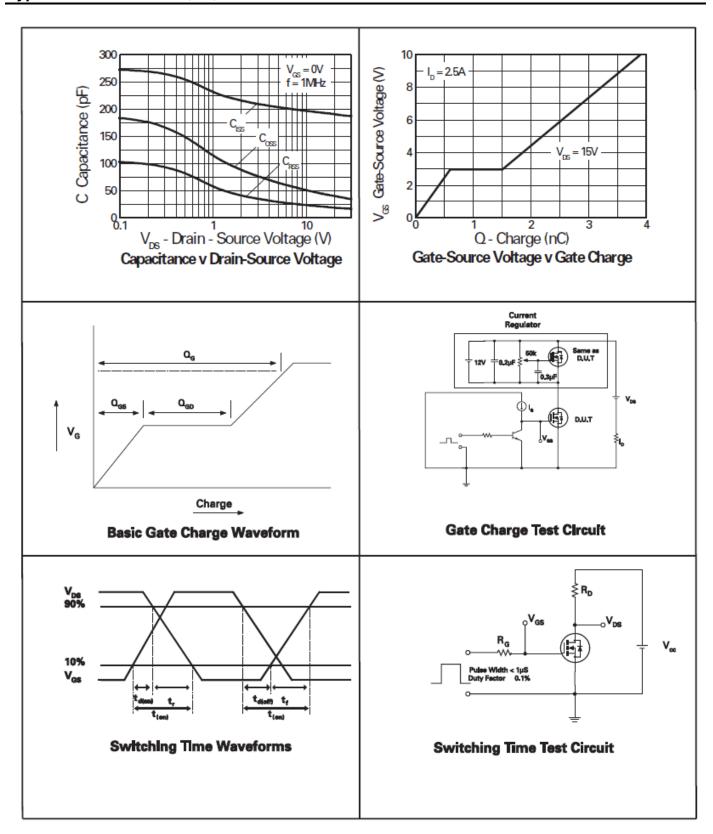


Typical Characteristics (cont.)





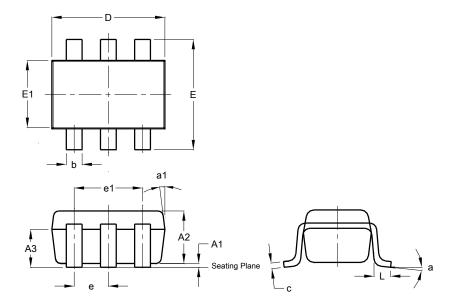
Typical Characteristics (cont.)





Package Outline Dimensions

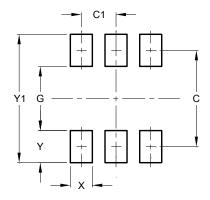
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



SOT26							
Dim	Min	Max	Тур				
A1	0.013	0.10	0.05				
A2	1.00	1.30	1.10				
A3	0.70	0.80	0.75				
b	0.35	0.50	0.38				
С	0.10	0.20	0.15				
D	2.90	3.10	3.00				
е	-	-	0.95				
e1	-	-	1.90				
Е	2.70	3.00	2.80				
E1	1.50	1.70	1.60				
L	0.35	0.55	0.40				
а	-	-	8°				
a1	-	-	7°				
All Dimensions in mm							

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	2.40
C1	0.95
G	1.60
Х	0.55
Y	0.80
Y1	3.20



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